

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-5. (Canceled)

6. (Currently Amended) A pseudo wafer structure comprising:

a plurality of semiconductor chips each being a tested known good die and having at least their electrodes formed solely on one surface thereof, wherein the one surface at which the electrodes are formed is releasably adhered to an adhesive layer of material that is secured to a substrate, wherein interspaces between each individual one of said chips and surfaces opposite the electrodes thereof are continuously covered with protective material, and the chips are bonded with each other via the protective material to thereby form the pseudo-wafer, there being substantially none of the protective material formed on the one surface at which the electrodes are formed, and further wherein the adhesive layer of material is comprised of a material which loses its adhesive characteristics upon application of a specified treatment.

7. (Original) The pseudo wafer according to claim 6 wherein said protective material comprises either one of an organic insulating resin and an inorganic insulating material.

Claims 8-9 (Cancelled).

Appl. No. 09/841,582
Amdt. Dated March 2, 2009
Reply to Office Action of August 29, 2008

10. (Currently Amended). The pseudo wafer according to claim 6, wherein the adhesive properties of said adhesive layer of material ~~sheet~~ are released upon the application of ultra violet light.